

	Type	Hits	Search Text	DBs
1	BRS	21045	("chip on chip" or (stack\$3 or mount\$3 or dual or double) adj (chip or die or semiconductor or IC))	USPAT; JPO
2	BRS	2460	("chip on chip" or (stack\$3 or dual or double) adj (chip or die or semiconductor or IC))	USPAT; JPO
3	BRS	1705	("chip on chip" or (stack\$3 or dual or double) near (chip or die or semiconductor or IC)) and lead	USPAT; JPO
4	BRS	1	"4251852".PN.	USPAT
5	BRS	79	"MOS" near (chip or die or semiconductor or IC) and lead and power near (electrode or pad or terminal or connector)	USPAT; JPO
6	BRS	4	"MOSgated" near (chip or die or semiconductor or IC) and power near (electrode or pad or terminal or connector)	USPAT; JPO
7	BRS	12	5147815.pn. or 11317488.pn. or 10256470.pn. or 5596225.pn. or 6175149.pn. or 6133067.pn. or 6313527.pn. or 6344687.pn. or 6353265.pn. or 5719436.pn. or 5793108.pn. or 5625226.pn.	USPAT; JPO
8	BRS	399	(257/670 or 257/671 or 257/676 or 257/686 or 257/685) and ("chip on chip" or (stack\$3 or dual or double) near (chip or die or semiconductor or IC)) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	372	(257/689 or 257/713 or 257/777 or 257/778 or 257/783 or 257/787) and ("chip on chip" or (stack\$3 or dual or double) near (chip or die or semiconductor or IC)) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	211	(361/760 or 438/108 or 438/109) and ("chip on chip" or (stack\$3 or dual or double) near (chip or die or semiconductor or IC)) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB